



Form 1449 (Modified) Information Disclosure Statement By Applicant (Use Several Sheets if Necessary)	Atty Docket No.	Application No.:
	NSC1P194D1/P04836D1	NEW
	Applicant:	
	MOSTAFAZADEH	
Filing Date	Group	
HEREWITH	UNASSIGNED	

U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
	1	6,261,864	7/17/01	Jung et al.			
	2	6,451,627	7/17/02	Coffman			
	3	6,306,685	10/23/01	Liu et al.			
	4	6,333,252	12/25/01	Jung et al.			
	5	5,656,550	8/12/97	Tsuji et al.			
	6	5,759,874	6/2/98	Okawa			
	7	5,585,195	12/17/96	Shmiada			
	8	6,034,422	3/7/00	Horita et al.			
	9	6,342,730	1/29/02	Jung et al.			
	10	6,238,952	5/29/01	Lin			
	11	5,895,234	04/99	Taniguchi et al.			
	12	6,100,594	08/00	Fukui et al.			
	13	6,355,507	03/02	Fanworth, Warren M.			
	14	6,177,288	01/01	Takiar, Hem P.			
	15	6,255,740	07/01	Tsuji et al.			
	16	5,866,948	02.02.99	Murakami et al.			
	17	6,258,626	07-2001	Wang et al.			
	18	6,157,080	12-2000	Tamaki et al.			
	19	6,247,229 B1	06/19/01	Glenn			
	20	6,358,778 B1	03/19/02	Shinohara			
	21	5,830,800	11/03/98	Lin			
	22	5,847,458	12/08/98	Nakamura et al.			
	23	5,923,080	07/13/99	Chun			
	24	5,998,875	12/07/99	Bodö			
	25	6,306,684 B1	10/23/01	Richardson et al.			
	26	6,307,755 B1	10/23/01	Williams et al.			
	27	6,316,837 B1	11/13/01	Song			
	28	6,130,473	10/10/00	Mostafazadeh et al.			

Foreign Patent or Published Foreign Patent Application


Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub- class	Translation	
							Yes	No



8/17/04

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Filing Date	Group	
HEREWITH	UNASSIGNED	

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
KP	29	U.S. Patent Application No. 09/528,540, entitled "Leadless Packaging Process Using a Conductive Substrate", filed March 20, 2000, inventor(s): Bayan et al.
↓	30	U.S. Patent Application No. 09/698,784, entitled "Flip Chip Scale Package", filed October 26, 2000, inventor(s): Shahram Mostafazadeh
KP	31	U.S. Patent Application No. 09/698,736, entitled "Chip Scale Pin Array", filed October 26, 2000, inventor(s): Shahram Mostafazadeh
Examiner		
	Date Considered	8/17/04

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.